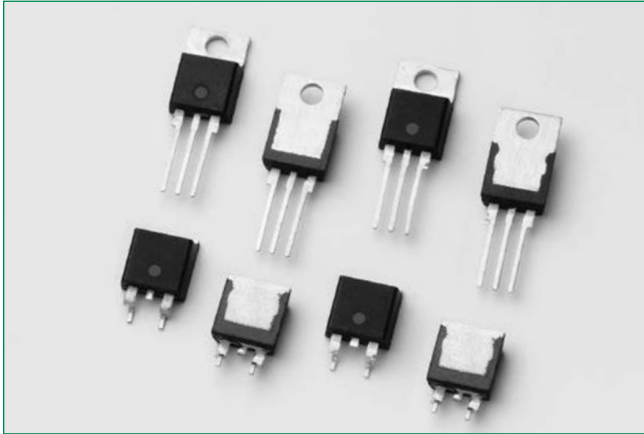


# SVxx25xxQ Series

## 25 Amp High Junction Temperature SCRs



### Description

The SVxx25xxQ high temperature SCR series is ideal for uni-directional switch applications such as phase control in heating, motor speed controls, converters/rectifiers and inrush current controllers.

These SCRs have a low gate current, (IGT) trigger level of 6mA and 10mA maximum at approximately 1.5V for SVxx25x1Q and SVxx25x2Q, respectively.

### Features & Benefits

- Halogen free and RoHS compliant
- 150°C maximum junction temperature
- High dv/dt performance
- Low turn off time
- Electrically isolated “L - Package” is UL 1557 recognized for 2500 VRMS
- Surge capability up to 350 A at 60 Hz half cycle

### Additional Information



Resources



Accessories



Samples

### Agency Approval

Agency	Agency File Number
	E71639*

\* - L Package Only

### Main Features

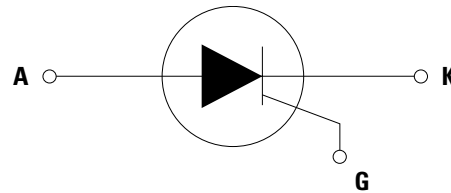
Symbol	Value	Unit
$I_{T(RMS)}$	25	A
$V_{DRM}/V_{RRM}$	600	V
$I_{GT}$	6 to 10	mA

### Applications

Typical applications include AC Generator (ACG) rectifiers, battery voltage regulators, generic converters, inrush current controller in various AC to DC applications and soft starter for low power AC motor. Additional applications include controls for power tools, home/brown good and white goods appliances.

Internally constructed isolated packages offered for ease of heat sinking with high isolation voltage.

### Schematic Symbol



# SVxx25xxQ Series

## 25 Amp High Junction Temperature SCRs

### Absolute Maximum Ratings

Symbol	Parameter	Test Conditions	Value	Unit
$V_{DSM}/\sqrt{t_{RSM}}$	Peak non-repetitive blocking voltage	$P_W = 100 \mu s$	800	V
$I_{T(RMS)}$	RMS on-state current	SVxx25LxQ $T_C = 100^\circ C$ SVxx25RxQ $T_C = 125^\circ C$ SVxx25NxQ	25	A
$I_{T(AV)}$	Average on-state current	SVxx25LxQ $T_C = 100^\circ C$ SVxx25RxQ $T_C = 125^\circ C$ SVxx25NxQ	16	A
$I_{TSM}$	Peak non-repetitive surge current	single half cycle; $f = 50 Hz$ ; $T_J$ (initial) = $25^\circ C$	300	A
		single half cycle; $f = 60 Hz$ ; $T_J$ (initial) = $25^\circ C$	350	
$I^2t$	$I^2t$ Value for fusing	$t_p = 8.3 ms$	510	$A^2s$
$di/dt$	Critical rate of rise of on-state current	$f = 60 Hz$ ; $T_J = 150^\circ C$	125	$A/\mu s$
$I_{GM}$	Peak gate current	$T_J = 150^\circ C$	4	A
$P_{G(AV)}$	Average gate power dissipation	$T_J = 150^\circ C$	0.8	W
$T_{stg}$	Storage temperature range		-40 to 150	$^\circ C$
$T_J$	Operating junction temperature range		-40 to 150	$^\circ C$

Note: xx=voltage/10, x=sensitivity

### Electrical Characteristics (T<sub>J</sub> = 25°C, unless otherwise specified)

Symbol	Test Conditions		SVxx25x1Q	SVxx25x2Q	Unit
$I_{GT}$	$V_D = 12V$ $R_L = 60 \Omega$	MAX.	6	10	mA
		MIN.	2	5	
$V_{GT}$	$V_D = 12V$ $R_L = 60 \Omega$	MAX.	1.5	1.5	V
$dv/dt$	$V_D = 67\% V_{DRM}$ ; gate open; $T_J = 125^\circ C$	MIN.	400	800	$V/\mu s$
	$V_D = 67\% V_{DRM}$ ; gate open; $T_J = 150^\circ C$		200	400	
$V_{GD}$	$V_D = V_{DRM}$ $R_L = 3.3 k\Omega$ $T_J = 150^\circ C$	MIN.	0.2	0.2	V
$I_H$	$I_T = 400 mA$ (initial)	MAX.	25	40	mA
$t_q$	$I_T = 2A$ ; $t_p = 50 \mu s$ ; $dv/dt = 5V/\mu s$ ; $di/dt = 30A/\mu s$	MAX.	12	12	$\mu s$
$t_{gt}$	$I_G = 2 \times I_{GT}$ $P_W = 15 \mu s$ $I_T = 50A$	TYP.	2.6	2.6	$\mu s$

Note: xx=voltage/10, x=package

### Static Characteristics

Symbol	Test Conditions	Value	Unit
$V_{TM}$	$I_T = 50A$ ; $t_p = 380 \mu s$	MAX.	1.7
$I_{DRM} / I_{RRM}$	$V_{DRM} = V_{RRM}$	MAX.	10
	$T_J = 25^\circ C$		1000
	$T_J = 150^\circ C$		4000

### Thermal Resistances

Symbol	Parameter	Value	Unit
$R_{\theta(JC)}$	Junction to case (AC)	SVxx25RxQ SVxx25NxQ	1.3
		SVxx25LxQ	2.5

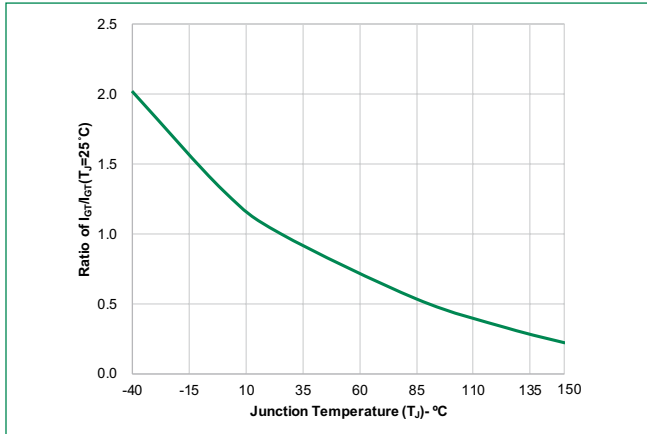
Note: xx=voltage/10, x=sensitivity

# SVxx25xxQ Series

## 25 Amp High Junction Temperature SCRs

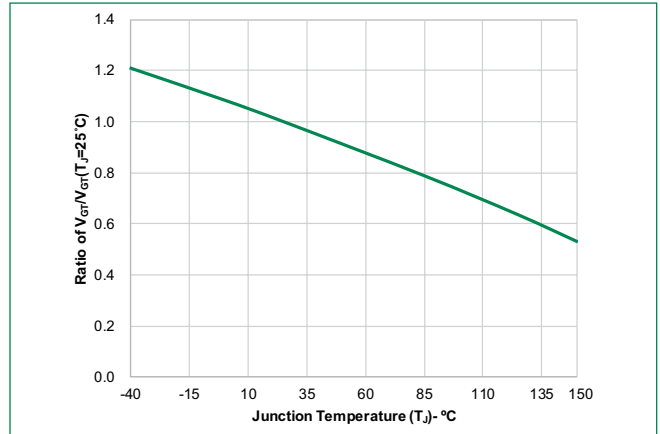
**Figure 1:**

Normalized DC Gate Trigger Current vs. Junction Temperature



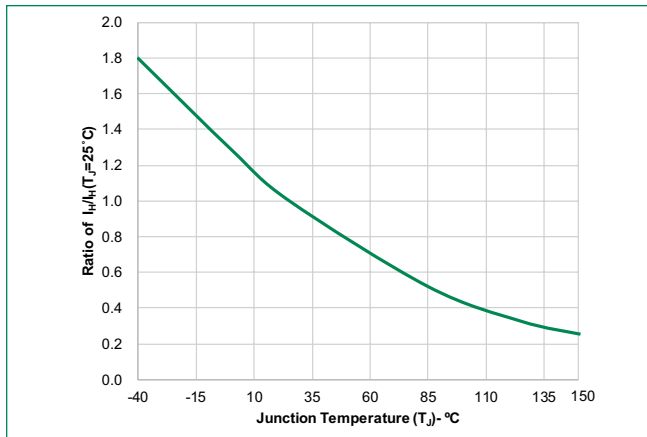
**Figure 2:**

Normalized DC Gate Trigger Voltage vs. Junction Temperature



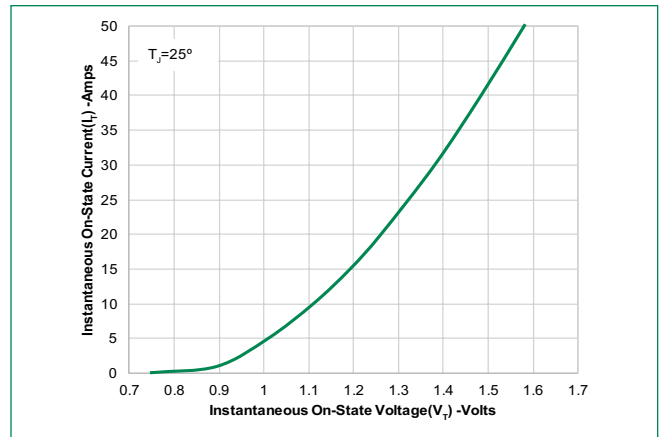
**Figure 3:**

Normalized DC Holding Current vs. Junction Temperature



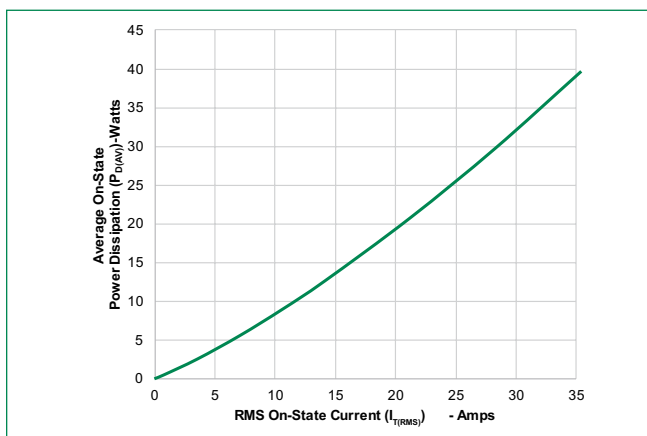
**Figure 4:**

On-State Current vs. On-State Voltage (Typical)



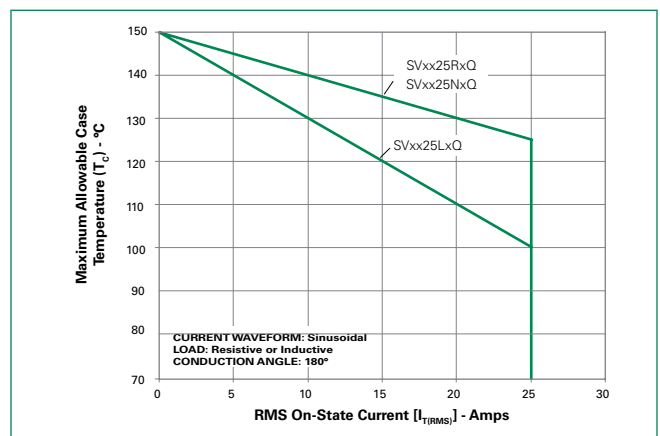
**Figure 5:**

Power Dissipation (Typical) vs. RMS On-State Current



**Figure 6:**

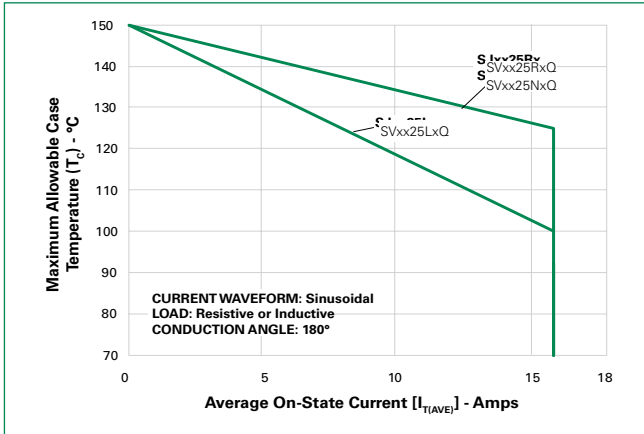
Maximum Allowable Case Temperature vs. RMS On-State Current



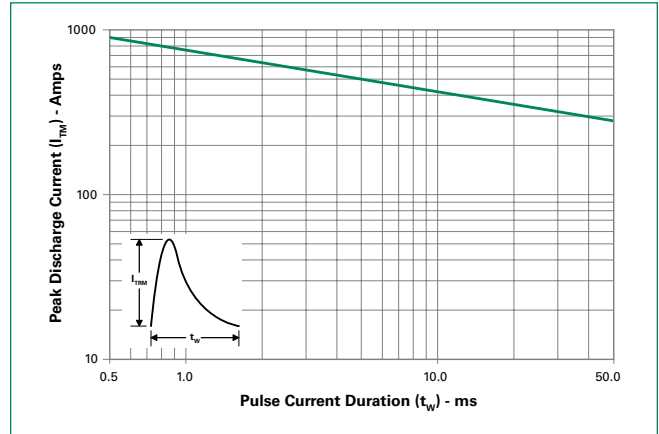
# SVxx25xxQ Series

## 25 Amp High Junction Temperature SCRs

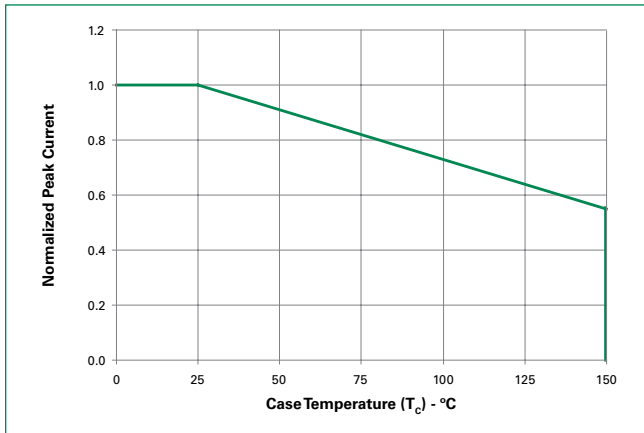
**Figure 7:**  
Maximum Allowable Case Temperature vs. Average On-State Current



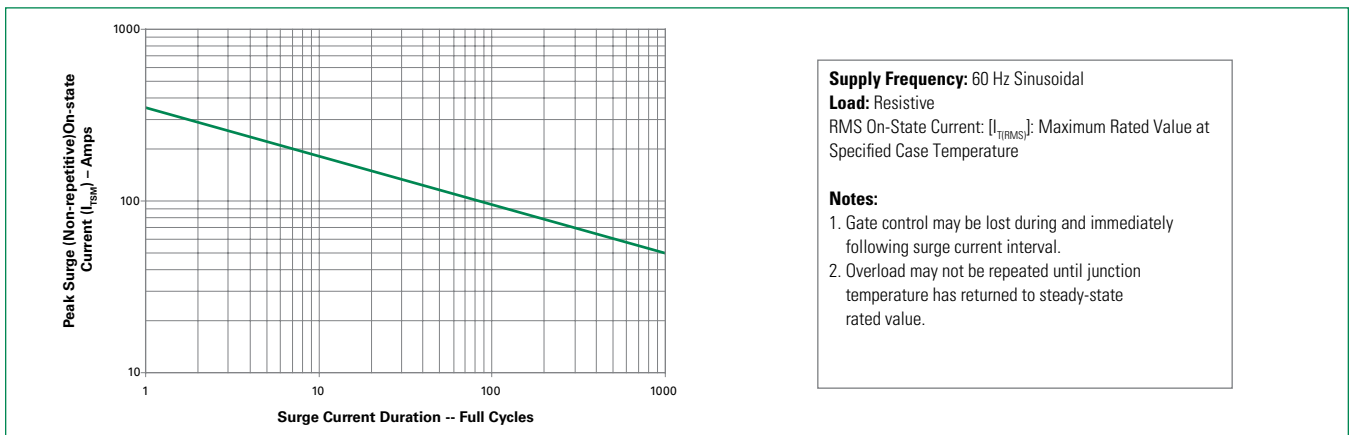
**Figure 8:**  
Peak Capacitor Discharge Current



**Figure 9:**  
Peak Capacitor Discharge Current Derating



**Figure 10:**  
Surge Peak On-State Current vs. Number of Cycles

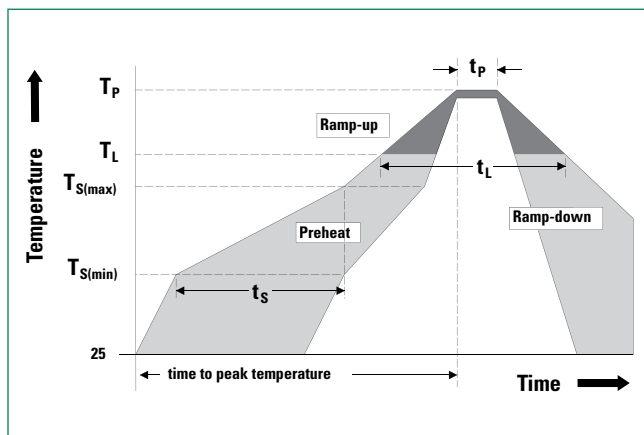


# SVxx25xxQ Series

## 25 Amp High Junction Temperature SCRs

### Soldering Parameters

<b>Reflow Condition</b>		Pb – Free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 180 secs
<b>Average ramp up rate (Liquidus Temp) (<math>T_L</math>) to peak</b>		5°C/second max
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>		5°C/second max
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Time ( $t_L$ )	60 – 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>		260 <sup>+0/-5</sup> °C
<b>Time within 5°C of actual peak Temperature (<math>t_p</math>)</b>		20 – 40 seconds
<b>Ramp-down Rate</b>		5°C/second max
<b>Time 25°C to peak Temperature (<math>T_p</math>)</b>		8 minutes Max.
<b>Do not exceed</b>		280°C



### Physical Specifications

<b>Terminal Finish</b>	100% Matte Tin-plated
<b>Body Material</b>	UL Recognized compound meeting flammability rating V-0
<b>Lead Material</b>	Copper Alloy

### Design Considerations

Careful selection of the correct component for the application's operating parameters and environment will go a long way toward extending the operating life of the Thyristor. Good design practice should limit the maximum continuous current through the main terminals to 75% of the component rating. Other ways to ensure long life for a power discrete semiconductor are proper heat sinking and selection of voltage ratings for worst case conditions. Overheating, overvoltage (including  $dv/dt$ ), and surge currents are the main killers of semiconductors. Correct mounting, soldering, and forming of the leads also help protect against component damage.

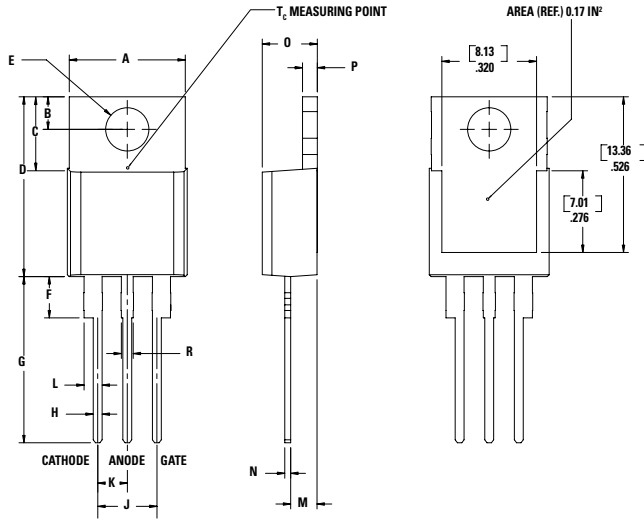
### Environmental Specifications

Test	Specifications and Conditions
<b>AC Blocking</b>	MIL-STD-750, M-1040, Cond A Applied Peak AC voltage @ 150°C for 1008 hours
<b>Temperature Cycling</b>	MIL-STD-750, M-1051, 1000 cycles; -55°C to +150°C; 15-min dwell-time
<b>Temperature/Humidity</b>	EIA / JEDEC, JESD22-A101 1008 hours; 160V - DC: 85°C; 85% rel humidity
<b>Resistance to Solder Heat</b>	MIL-STD-750 Method 2031
<b>Solderability</b>	ANSI/J-STD-002, category 3, Test A
<b>Lead Bend</b>	MIL-STD-750, M-2036 Cond E
<b>Moisture Sensitivity Level</b>	Level 1, JEDEC-J-STD-020D

# SVxx25xxQ Series

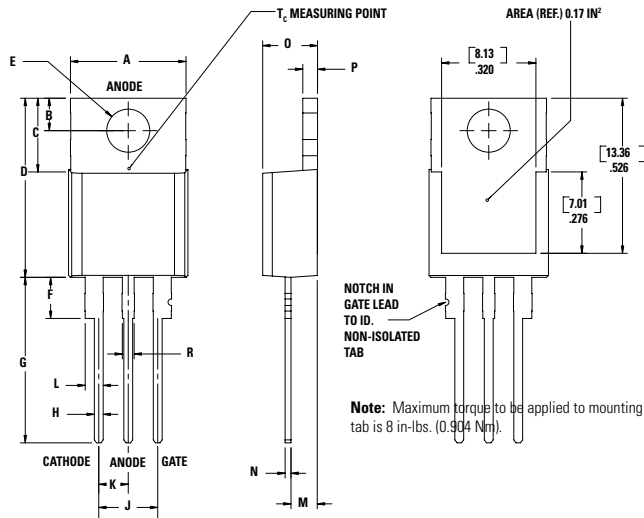
## 25 Amp High Junction Temperature SCRs

### Dimensions — TO-220AB (L-Package) — Isolated Mounting Tab



Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.380	0.420	9.65	10.67
B	0.105	0.115	2.67	2.92
C	0.230	0.250	5.84	6.35
D	0.590	0.620	14.99	15.75
E	0.142	0.147	3.61	3.73
F	0.110	0.130	2.79	3.30
G	0.540	0.575	13.72	14.61
H	0.025	0.035	0.64	0.89
J	0.195	0.205	4.95	5.21
K	0.095	0.105	2.41	2.67
L	0.060	0.075	1.52	1.91
M	0.085	0.095	2.16	2.41
N	0.018	0.024	0.46	0.61
O	0.178	0.188	4.52	4.78
P	0.045	0.060	1.14	1.52
R	0.038	0.048	0.97	1.22

### Dimensions — TO-220AB (R-Package) — Non-Isolated Mounting Tab Common with Center Lead

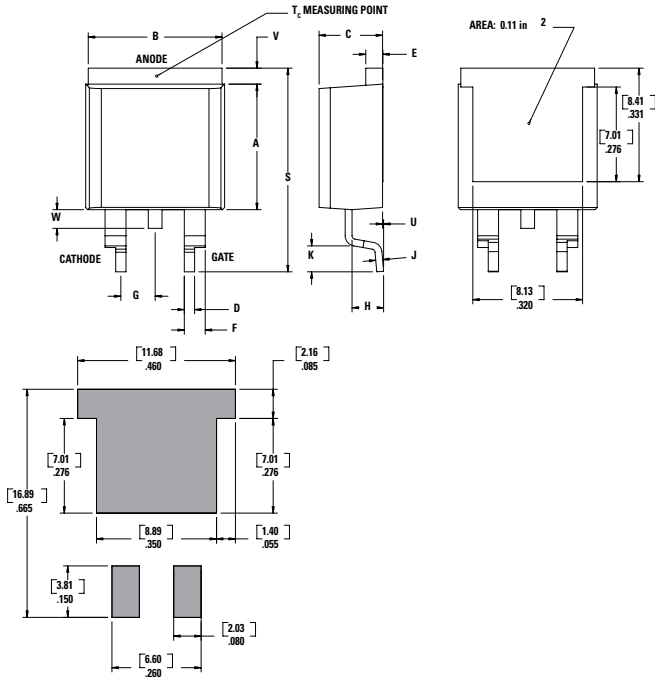


Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.380	0.420	9.65	10.67
B	0.105	0.115	2.67	2.92
C	0.230	0.250	5.84	6.35
D	0.590	0.620	14.99	15.75
E	0.142	0.147	3.61	3.73
F	0.110	0.130	2.79	3.30
G	0.540	0.575	13.72	14.61
H	0.025	0.035	0.64	0.89
J	0.195	0.205	4.95	5.21
K	0.095	0.105	2.41	2.67
L	0.060	0.075	1.52	1.91
M	0.085	0.095	2.16	2.41
N	0.018	0.024	0.46	0.61
O	0.178	0.188	4.52	4.78
P	0.045	0.060	1.14	1.52
R	0.038	0.048	0.97	1.22

# SVxx25xxQ Series

## 25 Amp High Junction Temperature SCRs

### Dimensions – TO- 263AB (N-package) — D2-Pak Surface Mount



Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.360	0.370	9.14	9.40
B	0.380	0.420	9.65	10.67
C	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
E	0.045	0.060	1.14	1.52
F	0.060	0.075	1.52	1.91
G	0.095	0.105	2.41	2.67
H	0.092	0.102	2.34	2.59
J	0.018	0.024	0.46	0.61
K	0.090	0.110	2.29	2.79
S	0.590	0.625	14.99	15.88
V	0.035	0.045	0.89	1.14
U	0.002	0.010	0.05	0.25
W	0.040	0.070	1.02	1.78

### Product Selector

Part Number	Voltage	Gate Sensitivity	Type	Package
	600V			
SVxx25L1Q	X	6mA	Standard SCR	TO-220L
SVxx25R1Q	X	6mA	Standard SCR	TO-220R
SVxx25N1Q	X	6mA	Standard SCR	TO-263
SVxx25L2Q	X	10mA	Standard SCR	TO-220L
SVxx25R2Q	X	10mA	Standard SCR	TO-220R
SVxx25N2Q	X	10mA	Standard SCR	TO-263

Note: xx = Voltage/10

### Packing Options

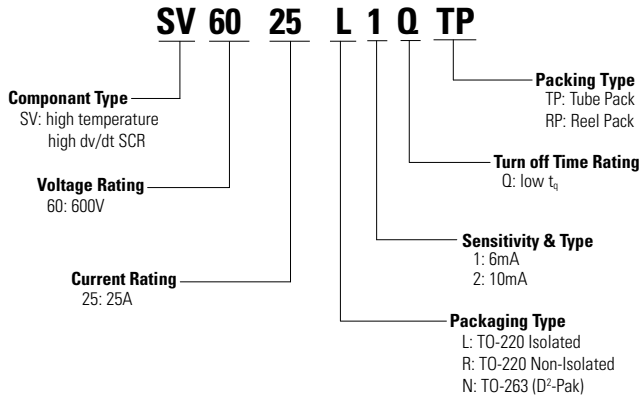
Part Number	Marking	Weight	Packing Mode	Base Quantity
SVxx25LxQTP	SVxx20Lx	2.2g	Tube	1000 (50 per tube)
SVxx25RxQTP	SVxx20Rx	2.2g	Tube	1000 (50 per tube)
SVxx25NxQTP	SVxx20Nx	1.6g	Tube	1000 (50 per tube)
SVxx25NxQRP	SVxx20Nx	1.6g	Embossed Carrier	500

Note: xx=voltage/10, x=sensitivity

# SVxx25xxQ Series

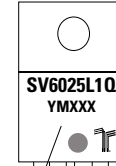
## 25 Amp High Junction Temperature SCRs

### Part Numbering System



### Part Marking System

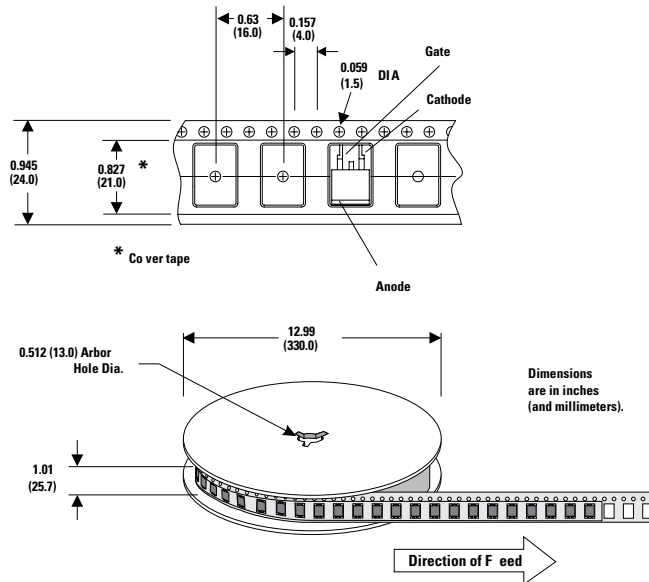
TO-220 AB - (L and R Package)  
TO-263 AB - (N Package)



**Date Code Marking**  
Y: Year Code  
M: Month Code  
XXX: Lot Trace Code

### TO-263 Embossed Carrier Reel Pack (RP) Specifications

Meets all EIA-481-2 Standards



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